

AMENDMENT UNDER 37 C.F.R. § 1.116
U.S. Application No.: 09/892,859

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AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A method for producing a cover tape for the electronic-part conveyance, said cover tape comprising:

a substrate;

at least one layer of a base coating layer and an intermediate layer, provided on the substrate;

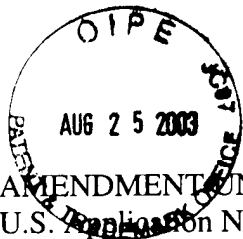
an adhesive layer, provided on said at least one layer of the base coating layer and the intermediate layer; and

a conductive layer formed on at least one of the rear surface of the substrate and the front surface of the adhesive layer, wherein the conductive layer has a thickness of from 1×10^{-4} to $0.007 \mu\text{m}$,

said method comprising forming said conductive layer on at least one of the rear surface of the substrate and the front surface of the adhesive layer by deposition.

2. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the conductive layer comprises at least one of Al, Cu, Ag, Ni, Ti, Fe, Cr, Zr, Ta, Zn, and an alloy containing at least one of Al, Cu, Ag, Ni, Ti, Fe, Cr, Zr, Ta and Zn.

3. (canceled).



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4. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the adhesive layer comprises 100 parts by weight of a base polymer and 2 to 100 parts by weight of a tackifier resin, and the adhesive layer has a thickness of 2 to 90 μm .

5. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the base coating layer comprises at least one of a urethane adhesive and an electrostatic induction preventing adhesive.

6. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the intermediate layer comprises a polyolefin based resin.

7. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein both surfaces of the cover tape have a surface resistivity of 10^2 to $10^{13} \Omega/\square$.

8. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the cover tape has a light transmittance of 60% or more.

9. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the cover tape has a frictional electrification voltage of 3,000 V or less at the adhesive layer side surface.

10. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the substrate has a melting point of 90°C or more.

11. (currently amended): A method for producing an electric-part-conveying member, said electric-part-conveying member comprising:

an electronic-part-storage member for storing an electronic part; and

a cover tape covering the electronic-part-storage member,

wherein the cover tape comprises at least four laminated layers of:

a substrate;

at least one layer of a base coating layer and an intermediate layer, provided on the substrate;

an adhesive layer, provided on said at least one layer of the base coating layer and the intermediate layer; and

a conductive layer formed on at least one of the rear surface of the substrate and the front surface of the adhesive layer by deposition, wherein the conductive layer has a thickness of from 1×10^{-4} to 0.007 μm .

said method comprising forming said conductive layer on at least one side of the rear surface of the substrate and the front surface of the adhesive layer by deposition.

12. (canceled).

13. (previously presented): The method for producing a cover tape for the electronic-part conveyance according to claim 1, wherein the deposition is by vacuum deposition.

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14. (previously presented): A cover tape for the electronic-part conveyance made by the method of claim 1.

15. (previously presented): An electric-part-conveying member made by the method of claim 11.